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Panasonic

PNZ331CL (PN331CL)

PIN Photodiode

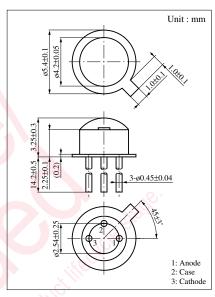
For optical fiber communication systems

Features

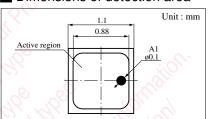
- TO-18 standard type package
- High coupling capability suitable for plastic fiber
- High quantum efficiency
- High-speed response

■ Absolute Maximum Ratings (Ta = 25°C)

Parameter	Symbol	Ratings	Unit
Reverse voltage (DC)	V_R	30	V
Power dissipation	$P_{\rm D}$	50	mW
Operating ambient temperature	T_{opr}	-25 to +85	°C
Storage temperature	T_{stg}	-30 to +100	°C ,



Dimensions of detection area



■ Electro-Optical Characteristics (Ta = 25°C)

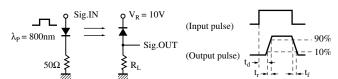
Parameter	Symbol	Conditions	min	typ	max	Unit
Dark current	I_{D}	$V_R = 10V$	-01/1	0.1	10	nA
Photo current	I_L	$V_R = 10V, L = 1000 lx^{*1}$	7	14		μΑ
Peak sensitivity wavelength	$\lambda_{ m P}$	$V_R = 10V$		900		nm
Response time	t_r, t_f^{*2}	$V_R = 10V$, $R_L = 50\Omega$	10.7	2		ns
Capacitance between pins	C_{t}	$V_R = 10V$	2	3		pF
Photodetection sensitivity	R	$V_R = 10V, \lambda = 800nm$		0.55		A/W
Acceptance half angle θ Measured from the optical axis to the half power point			70		deg.	
Photodetection surface shape	D	Effective detection area		□0.88		mm

Note 1) Spectral sensitivity: Sensitivity at wavelengths exceeding 400 nm as a percentage of maximum sensitivity is 100%

Note 2) This product is not designed to withstand electromagnetic radiation or heavy-charge particles.

Note 3) Difficult to guarantee compliance with moisture resistance standard (MIL-STD-202D)

^{*2} Switching time measurement circuit (see figure below)

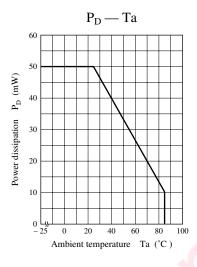


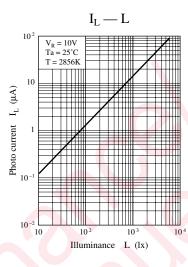
- t_d: Delay time
- $\rm t_r$: Rise time (Time required for the collector photo current to increase from 10% to 90% of its final value)
- $t_{\rm f}$: Fall time (Time required for the collector photo current to decrease from 90% to 10% of its initial value)

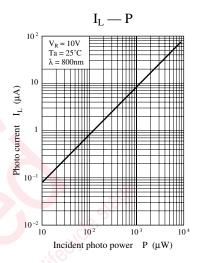
Note) The part number in the parenthesis shows conventional part number.

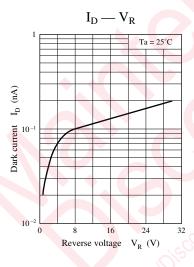
^{*1} Measurements were made using a tungsten lamp (color temperature T = 2856K) as a light source.

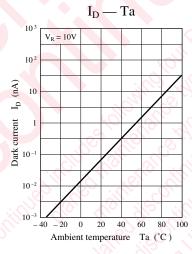
PIN Photodiodes PNZ331CL

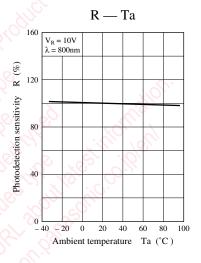


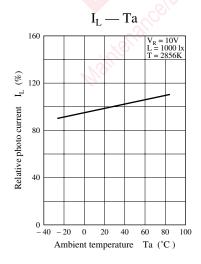


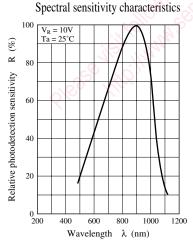


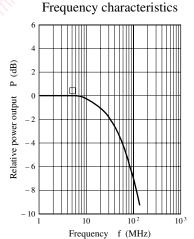






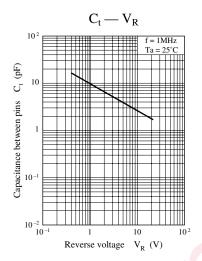


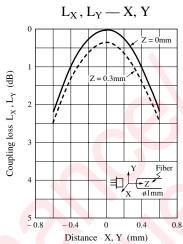


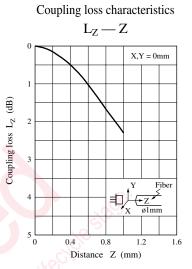


PNZ331CL PIN Photodiodes

Coupling loss characteristics







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